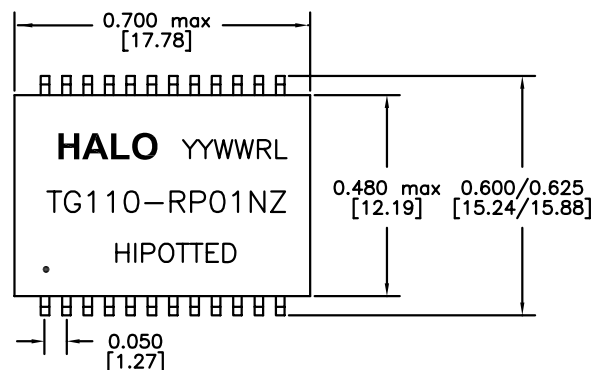
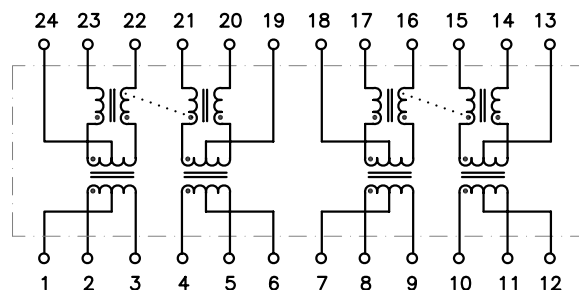


DIMENSIONS: Inch [mm]  
CO-PLANARITY: 0.004 [0.10]  
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



## PART NO. : TG110-RP01NZRL

DUAL-PORT FAST OR SINGLE GIGABIT ETHERNET  
COMPLIANT WITH IEEE802.3af REQUIREMENTS

350mA DC CURRENT CARRYING CAPACITY  
ON LINE SIDE FOR PoE APPLICATIONS

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS  
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C

## ELECTRICAL SPECIFICATIONS @25° C

|                          |             |
|--------------------------|-------------|
| URNS RATIO               | 1CT:1CT ±2% |
| OCL (100KHz,0.1Vrms,8mA) | 350µH min   |
| DCR (CHIP SIDE)          | 0.9Ω max    |
| INSERTION LOSS           |             |
| 1-100MHz                 | -1.1dB max  |
| RETURN LOSS              |             |
| 1-40MHz                  | -18dB min   |
| 60MHz                    | -14dB min   |
| 80MHz                    | -12dB min   |
| 100MHz                   | -10dB min   |
| CROSSTALK                |             |
| 1-100MHz                 | -38dB typ   |
| CMR                      |             |
| 1-100MHz                 | -38dB typ   |
| ISOLATION                | 1,500Vrms   |



**HALO/PBL**

CALIFORNIA, USA  
KOWLOON, HONG KONG  
SINGAPORE

| TITLE    | ISOLATION MODULE           | SIGNATURES        | DATE     | REV. | DESC.         | DATE     |
|----------|----------------------------|-------------------|----------|------|---------------|----------|
| FOR      | FAST/GIGABIT ETHERNET, PoE | DRAWN PETER LU    | 11/22/05 | A    | FIRST ISSUE   | 11/22/05 |
| PART NO. | TG110-RP01NZRL             | CHECKED LEI KEONG | 2/15/06  | B    | PROD. RELEASE | 2/15/06  |
| SCALE    | NONE                       | APPROVED PETER LU | 2/15/06  |      |               |          |
| PAGE     | 1 OF 1                     | FILE RP01NZRL.DWG |          |      |               |          |